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Particulate contamination that can affect to the device yield were generated during PECVD process. In order to generate high yield, the analysis of nano-scale particle contamination is an important factor in the semiconductor and display panel manufacturing. Since those deposition methods are progressed mostly in a vacuum conditions, a particle beam mass spectrometer (PBMS) to understand the particle size and the number concentration distributed inside vacuum was installed to the PECVD reactor exhaust for contaminant particle monitoring. To improve the dry etch strength of amorphous carbon layer (ACL) for hardmask applications, layers were deposited under various condition changes such as the plasma power, carbonaceous gas flow rate, nitrogen and boron dopant flow rate. To identify the contribution of flow conditions to the measured particle size distributions, numerical analysis for the particle flow from the deposition chamber to PBMS inlet was also progressed. From the results, larger particle sizes and higher generated particle concentrations were observed for the deposition processes of B-doped ACLs, whereas the N-doped ACL deposition process revealed smaller particle sizes and lower particle concentrations. Numerical analysis shows that the trapped or escaped particle counts inside each parts are closely related with the total gas flow rate by showing separated distribution between higher gas flow rate and lower gas flow rate.